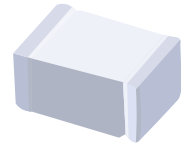
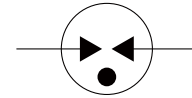


FEATURES

- | Surface Mounting Design 4.5*3.2*2.7mm
- | High Current Handling Capability 2000A @ 8/20 μs
- | Low Capacitance and Insertion Loss
- | Quick Response and Long Service Life
- | Moisture sensitivity level:Level 1



4.5*3.2*2.7mm





Schematic Symbol

APPLICATION INFORMATION

- | Communication equipment.
- | Repeaters,Modems
- | Telephone Interface,Line cards.
- | Data communication equipment.

AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
	UL Certificated E505857

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

ELECTRICAL PARAMETER

Parameter	Condition	Rating	Unit
DC Blocking Voltage 1)2)	100V/s	160-240	V
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ≤750	V
	At 1kV/μs	Typical values of distribution ≤700	V
Impulse Discharge Current 3)	8/20μs	2000	A
Insulation Resistance	DC=100V	≥ 1.0	GΩ
Capacitance at 1MHz	V _{DC} =0.5V	≤ 0.5	pF
Operating And Storage Temperature		-40-125	°C

1) At delivery AQL 0.65 level II GB/T 2828.1-2003

2) In ionized mode

3) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

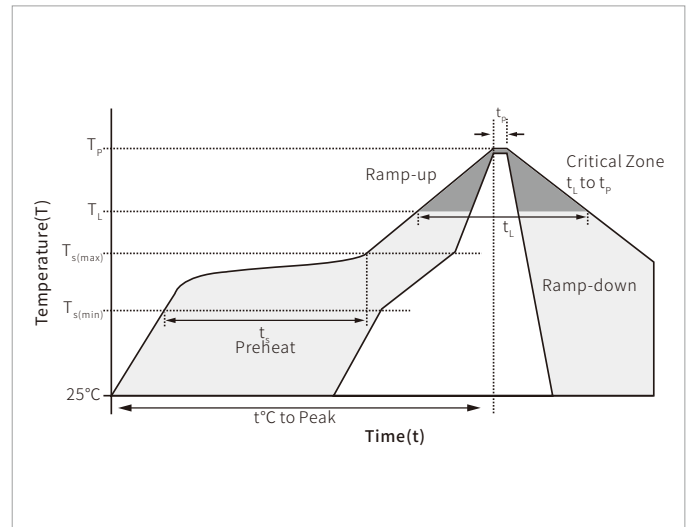
ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85°C ; Time:2H
Low Temperature Storage Test	Temperature: -40°C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude:0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260±5°C; Time of dip soldering: 10s, 1time

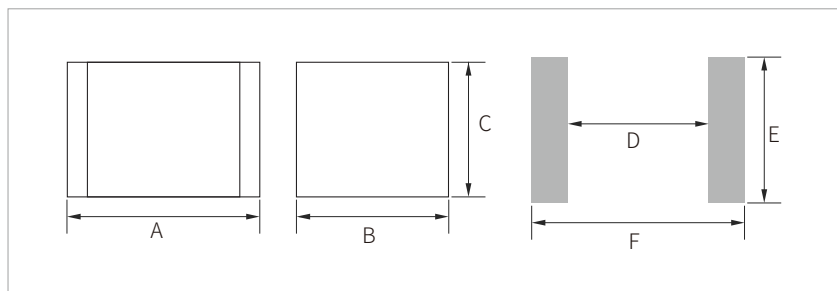
NOTE:Up-screen program can be specified by customer' s request via contacting Semiware service

REFLOW PROFILE

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time(min to max)	60 – 180 secs
Average ramp up rate (Liquidus)Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time(min to max)(t_s)	60 – 150 seconds
Peak Temperature (T_p)		260 °C
Time within 5°C of actual peak Temperature (t_p)		20-40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

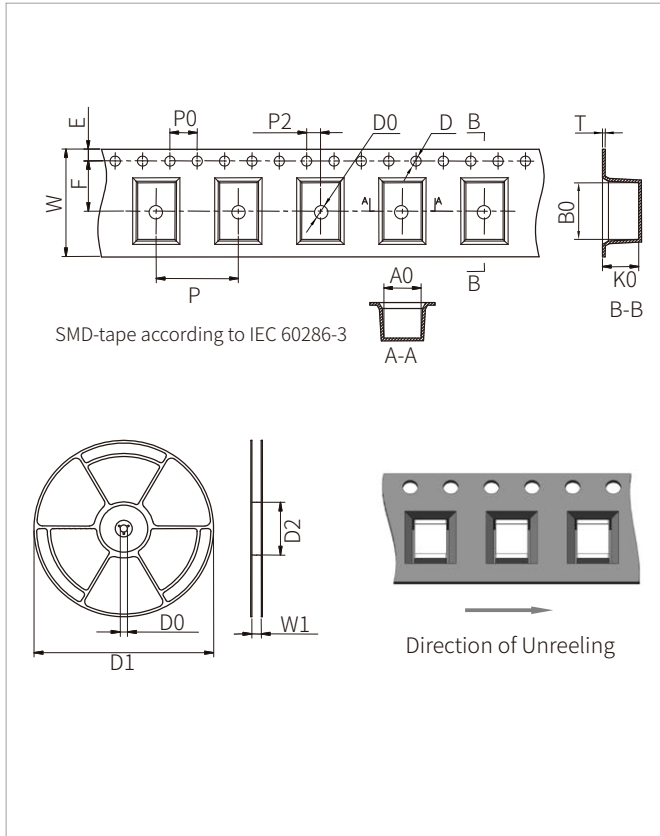


PRODUCT DIMENSIONS AND RECOMMENDED SOLDERING PAD



Ref.	mm
A	4.5±0.3mm
B	3.2±0.3mm
C	2.7±0.3mm
D	2.5mm
E	4.0mm
F	5.2mm

TAPE AND REEL SPECIFICATION



Ref.	Dimensions	
	Millimeters	Inches
W	12±0.3	0.472±0.012
A0	3.5±0.1	0.138±0.004
B0	5.3±0.1	0.209±0.004
K0	2.9±0.1	0.114±0.004
P	8.0±0.1	0.315±0.004
F	5.5±0.1	0.217±0.004
E	1.75±0.1	0.069±0.004
D	1.5+0.1/-0.0	0.059+0.004/-0.0
P0	4±0.1	0.157±0.004
P2	2±0.1	0.079±0.004
T	0.35±0.05	0.014±0.002
D0	13.3±0.15	0.524±0.006
D1	330±2	12.992±0.079
D2	100+1/-2	3.937+0.039/-0.079
W1	12.5±0.4	0.492±0.016

ORDERING INFORMATION

Part Number	Size	QTY/Reel	Reel Size
G4532B200	4.5*3.2*2.7mm	2500PCS	13"

To find your local partner within Semiwell' s website : www.semiwell.com.cn

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